

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions and listings of claims in the application.

**COMPLETE LISTING OF THE CLAIMS:**

Claims 1-14 : (Canceled)

Claim 15 : (Currently Amended) A high frequency apparatus, comprising:

a) a movable wall having a support which carries an electrical conductive plate, and being an active surface during use; and

b) a plurality of contact fingers at a periphery of the movable wall and being integral with the conductive plate, the contact fingers being arranged to extend behind the support.

Claim 16 : (Previously Presented) The apparatus as claimed in claim 15, wherein the support has substantially the same area and shape as that of the conductive plate.

Claim 17 : (Previously Presented) The apparatus as claimed in claim 15, wherein the support is a framework.

Claim 18 : (Previously Presented) The apparatus as claimed in claim 15, wherein the active surface of the movable wall is defined by a single conductive plate.

Claim 19 : (Previously Presented) The apparatus as claimed in claim 15, wherein the contact fingers are arranged around the entire periphery of the movable wall.

Claim 20 : (Previously Presented) The apparatus as claimed in claim 15, wherein the movable wall is a tuning door for a resonant cavity.

Claim 21 : (Previously Presented) The apparatus as claimed in claim 15, wherein the conductive plate is constituted of beryllium copper.

Claim 22 : (Previously Presented) The apparatus as claimed in claim 15, wherein the conductive plate is gold plated.

Claim 23 : (Previously Presented) The apparatus as claimed in claim 15, wherein the conductive plate is silver plated.

Claim 24 : (Previously Presented) The apparatus as claimed in claim 15, wherein the conductive plate is fixed to the support by an adhesive.

Claim 25 : (Previously Presented) The apparatus as claimed in claim 15, wherein the conductive plate is fixed to the support by an adhesive tape.

Claim 26 : (Currently Amended) A method of manufacturing a movable wall for a high frequency apparatus, comprising the steps of:

- a) taking a plate of a conductive material;
- b) forming contact fingers at a periphery of the plate; and
- c) then mounting the plate on a support, and arranging the contact fingers to extend behind the support.

Claim 27 : (Previously Presented) The method as claimed in claim 26, wherein the step of forming the fingers is performed by photoetching.

Claim 28 : (Previously Presented) The method as claimed in claim 26, wherein the plate is constituted of beryllium copper.

Claim 29 : (Previously Presented) The method as claimed in claim 26, and the step of plating the plate with gold.

Claim 30 : (Previously Presented) The method as claimed in claim 26 and the step of plating the plate with silver.

Claim 31 : (Previously Presented) The method as claimed in claim 26, and the step of fixing the plate to the support by an adhesive.

Claim 32 : (Previously Presented) The method as claimed in claim 26, and the step of fixing the plate to the support by an adhesive tape.